

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} Vr	1,000	V
RMS Reverse Voltage	V _{R(RMS)}	700	V
Average Rectified Output Current (Note 5)@ $T_A = +40^{\circ}C$ (Note 6)@ $T_A = +40^{\circ}C$	lo	0.5 0.8	A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	IFSM	30	А
I ² t Rating for Fusing (1ms < t < 8.3ms)	l ² t	3.74	A ² S

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element)	R _{θJA}	101	°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	R _{0JL}	42	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	1,000	—	_	V	I _R = 5μA
Forward Voltage (Per Element)	VF	_	0.93	1.1	V	$I_F = 0.8A, T_A = +25^{\circ}C$
Leakage Current (Note 7) (Per Element)	I _R	_	0.2 21	5 500	μA	V _R = 1,000V, T _A = +25°C V _R = 1,000V, T _A = +125°C
Total Capacitance (Per Element)	Ст	_	8	—	pF	$V_{R} = 4V, f = 1.0MHz$

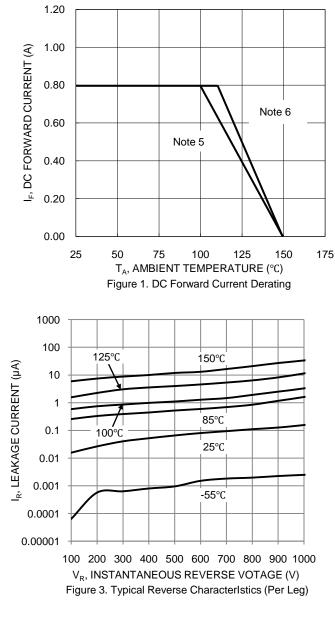
Notes:

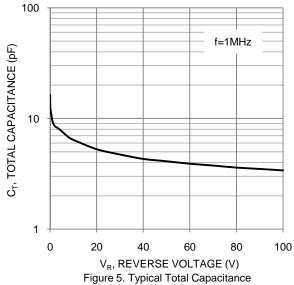
5. Device mounted on FR-4 substrate, 1"*1", 2oz, single-sided, PC boards with 0.1"*0.15" copper pad. 6. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad.

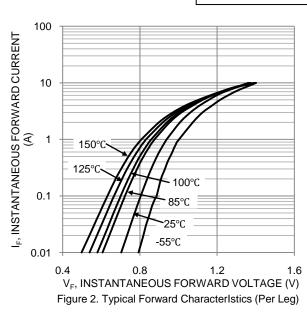
7. Short duration pulse test used to minimize self-heating effect.



MB10S







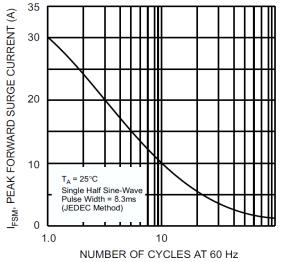
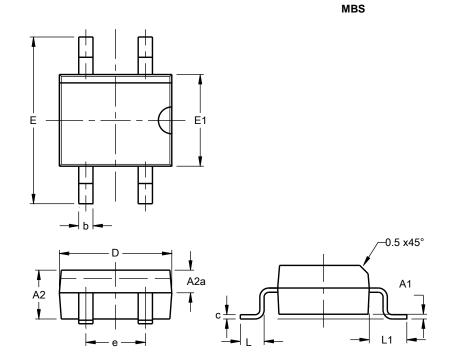


Figure 4. Maximum Peak Forward Surge Current (Per Leg)



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

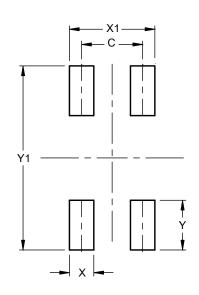


MBS						
Dim	Min	Max	Тур			
A1	-	0.20				
A2	2.30	2.70				
A2a	0.90	1.30				
b	0.50	0.70				
С	0.15	0.25				
D	4.50	4.95				
Е		7.00				
E1	3.60	4.10				
е	2.30	2.70				
L	0.60	1.10				
L1		1.70				
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

MBS



Dimensions	Value (in mm)
С	2.50
Х	1.00
X1	3.50
Y	2.15
Y1	7.50



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